Analog Devices Welcomes Hittite Microwave Corporation

NO CONTENT ON THE ATTACHED DOCUMENT HAS CHANGED
**MS8 (E) – 8 LEAD PLASTIC MSOP PACKAGE**

**MS8 (E) Package Outline Drawing**

**Package Information**

<table>
<thead>
<tr>
<th>Part Number</th>
<th>Package Body Material</th>
<th>Lead Finish</th>
<th>MSL Rating</th>
<th>Package Marking</th>
</tr>
</thead>
<tbody>
<tr>
<td>MS8</td>
<td>RoHS Compliant Mold Compound</td>
<td>Sn/Pb Solder</td>
<td>MSL1 [1]</td>
<td>HNNN XXXX</td>
</tr>
<tr>
<td>MS8E</td>
<td>RoHS Compliant Mold Compound</td>
<td>100% matte Sn</td>
<td>MSL1 [2]</td>
<td>HNNN XXXX</td>
</tr>
</tbody>
</table>

**NOTES:**
1. LEADFRAME MATERIAL: COPPER ALLOY
2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
3. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
4. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
5. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.

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For price, delivery, and to place orders, please contact Hittite Microwave Corporation:
20 Alpha Road, Chelmsford, MA 01824 Phone: 978-250-3343 Fax: 978-250-3373
Order On-line at www.hittite.com
Suggested MS8 (E) PCB Land Pattern

NOTES:
1. DIMENSIONS ARE IN INCHES [MILLIMETERS].
2. PAD WIDTH SHOWN IS FOR SOLDERING ONLY. BEYOND SOLDERING AREA ALL CONDUCTORS THAT CARRY RF AND MICROWAVE SIGNALS SHOULD HAVE 50 OHM CHARACTERISTIC IMPEDANCE.
**MS8G (E) Package Outline Drawing**

**Package Information**

<table>
<thead>
<tr>
<th>Part Number Suffix</th>
<th>Package Body Material</th>
<th>Lead Finish</th>
<th>MSL Rating</th>
<th>Package Marking[^1][^2]</th>
</tr>
</thead>
<tbody>
<tr>
<td>MSG8</td>
<td>RoHS Compliant Mold Compound</td>
<td>Sn/Pb Solder</td>
<td>MSL1[^1]</td>
<td>HNNN XXXX</td>
</tr>
<tr>
<td>MS8GE</td>
<td>RoHS Compliant Mold Compound</td>
<td>100% matte Sn</td>
<td>MSL1[^2]</td>
<td>HNNN XXXX</td>
</tr>
</tbody>
</table>

[^1]: Max peak reflow temperature of 235 °C
[^2]: Max peak reflow temperature of 260 °C
[^3]: 4-Digit lot number XXXX
[^4]: 3-Digit part number NNN
Suggested MS8G (E) PCB Land Pattern

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